PicoSec Kickoff Meeting Heidelberg Activities

Hans-Christian Schultz-Coulon Kirchhoff-Institut für Physik Universität Heidelberg

Main HD Involvement:

WP3: Electronics & Data Acquisition WP4: Detector Integration & Prototyping

Electronics & Data Acquisition (WP3)

KLauS: Charge Readout Chip [Kanäle für Ladungsauslese von SiPMs]

> AMS 350 nm CMOS technology SPI interface; tunable bias DAC High signal/noise ratio [>10, 40 fC signal charge]; Fast trigger available [pixel signal jitter < 1ns]; Large dynamic range up to 150pC

Klaus 2.0: Power pulsing; 12 channels ... First characterization done; functions as expected [Version 3: to be part of SPIROC III] [S. Callier et. al, IEEE NSS/MIC, 2009; 0.1109/NSSMIC.2009.5401891]

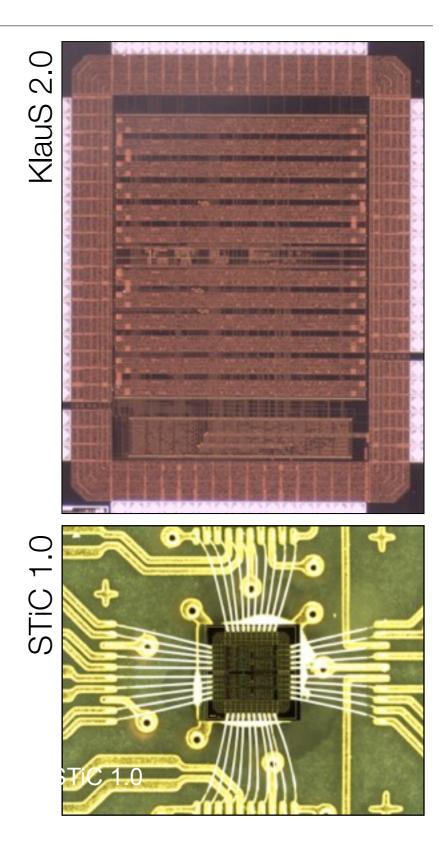
STIC: SiPM Timing Chip

[Fast Discrimination for ToF]

STiC 1.0: AMS 350 nm CMOS , 4 channels; Leading edge & Constant fraction trigger; Tunable bias DAC ~ 1 V; power < 10mW/ch Pixel jitter ~300 ps, time of flight capability

STiC 2.0: UMC 180 nm Differential design to explore timing limits ... Goal: Single pixel time resolution < 100 ps. [EndoToFPET-US project: STiC 2.0 + TDC ...]

W. Shen et. al, IEEE NSS/MIC, 2009; 10.1109/NSSMIC.2009.5401693



Electronics & Data Acquisition (WP3)

STIC Version 2.0 [EndoTofPET US; external PET plate]

> High precision timing measurement Leading edge trigger ToT energy measurement

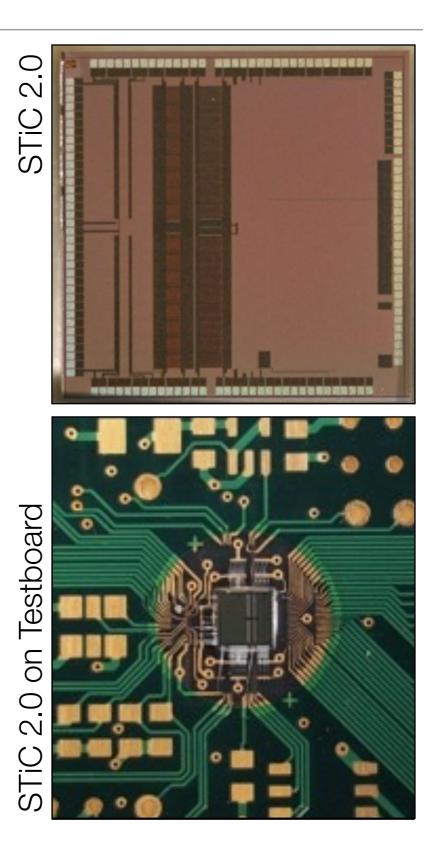
Technology: UMC 180 nm 16 channels; integrated TDC Full digital output

Review: June 20th Submission: End of July

STiC 2.0 Status:

Chip and test board available ...

First tests performed last week Investigations ongoing ...



Detector Integration & Prototyping (WP4)

HD Activities:

Simulation of Scintillator/SiPM-Systems Characterization of Scintillator/SiPM-Systems SiPM-Characterization

EndoToFPET detector integration & prototyping [with DESY/Hamburg]

Infrastructure:

SiPM Test Laboratory

Pulsed Laser System 2-arm PET-Prototype [@ DESY]

